

SVM-6151P

Basic Specifications • Features



Size W2960 x D2057 x H1777mm
Weight 3500kg ※Excluded Vacuum Pump

A high-rigidity frame structure that withstands high printing pressure.
An operation interface designed for workability and production efficiency.

- 24-inch Large Screen Monitor • movable touch panel
- Laser pointer for plate and substrate alignment

Basic Specifications

Workpiece size	610 x 510mm
Frame size	1100 x 1100mm
Vaccum level	100Pa
Printing Pressure	1200N
Alignment	Dual camera auto alignment

HLC-PCB

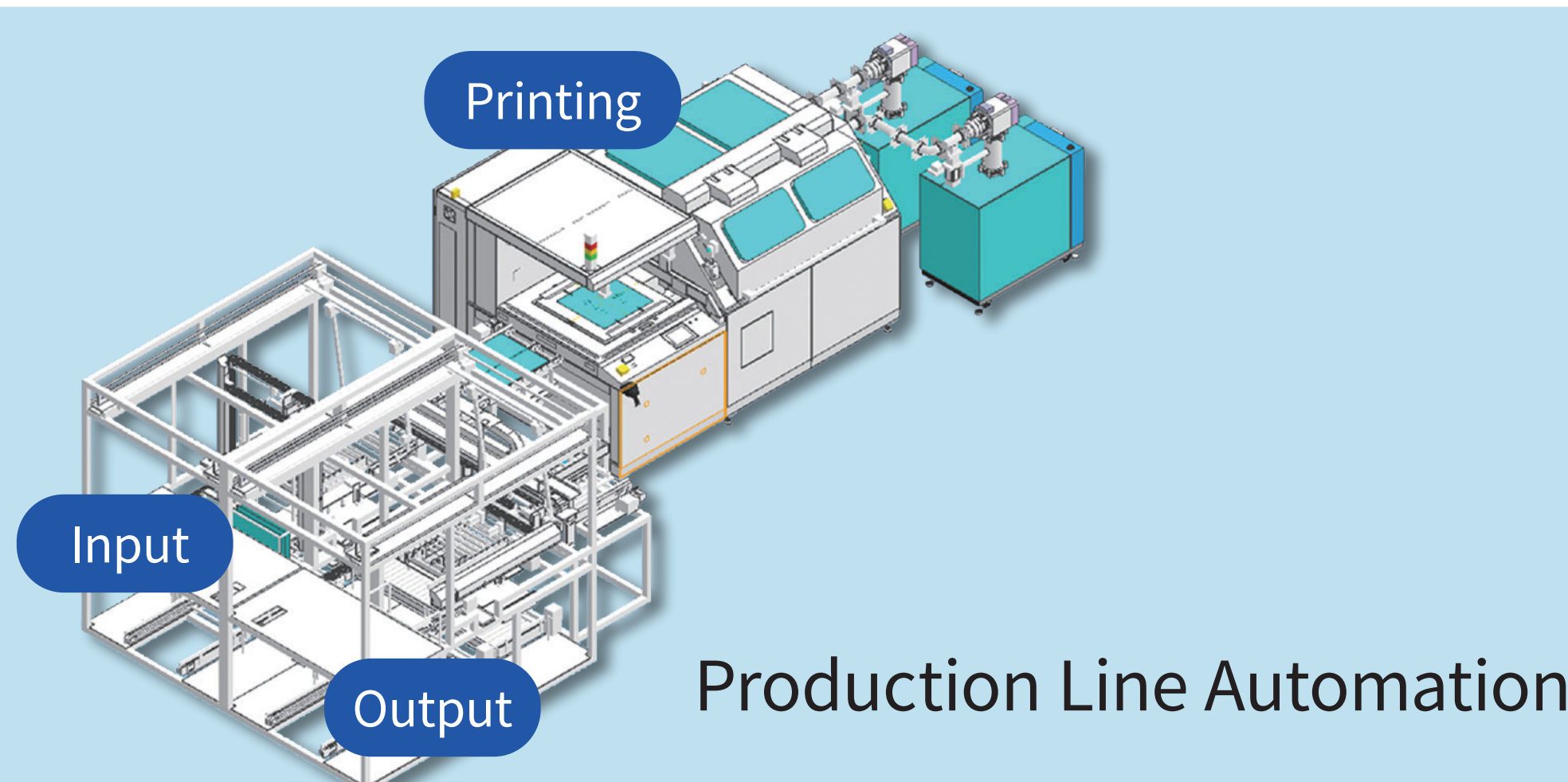
Glass Interposer

Semiconductor
Package Substrate

Glass Core Substrate

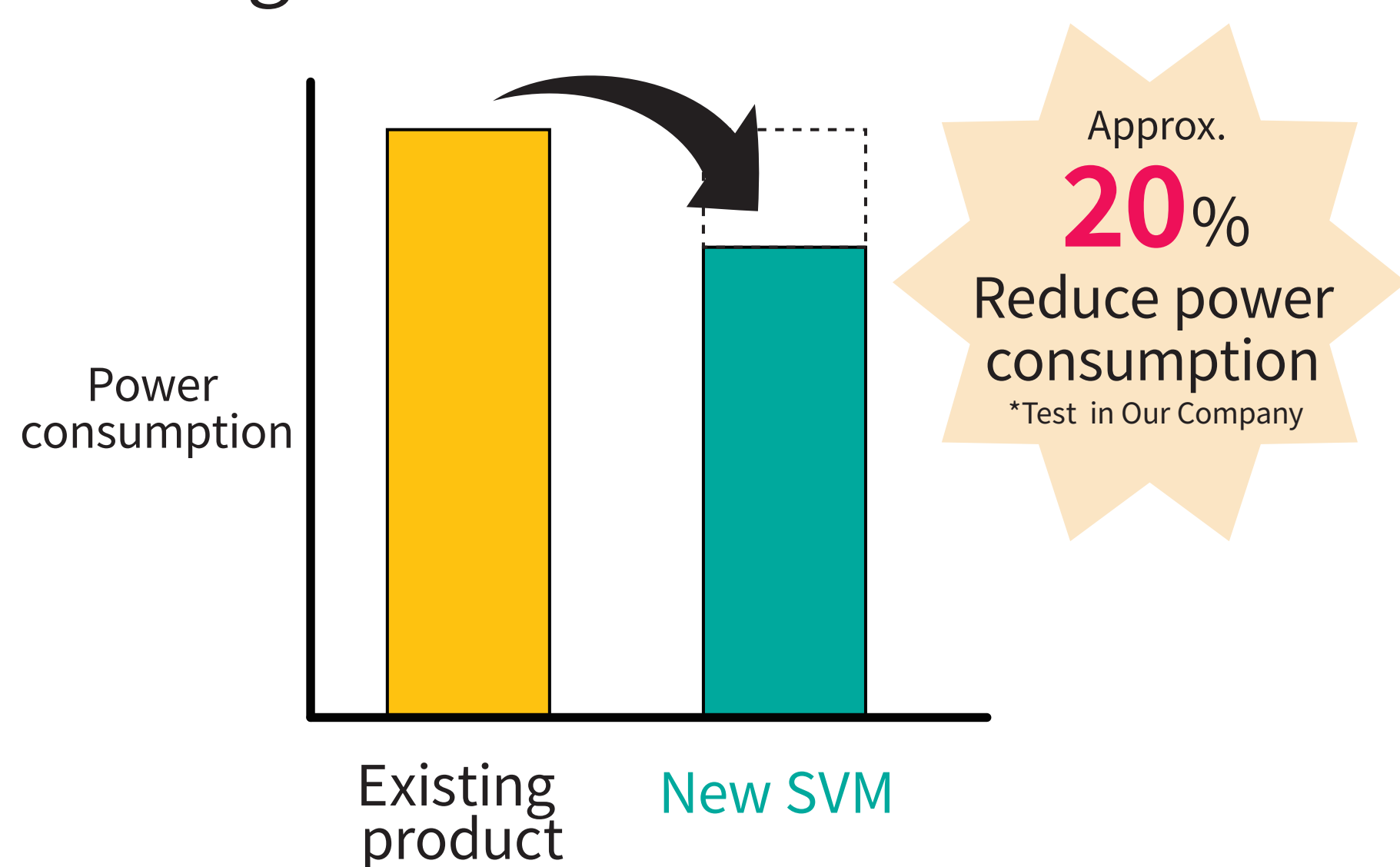
Probe Card Board

Electrostatic Chuck

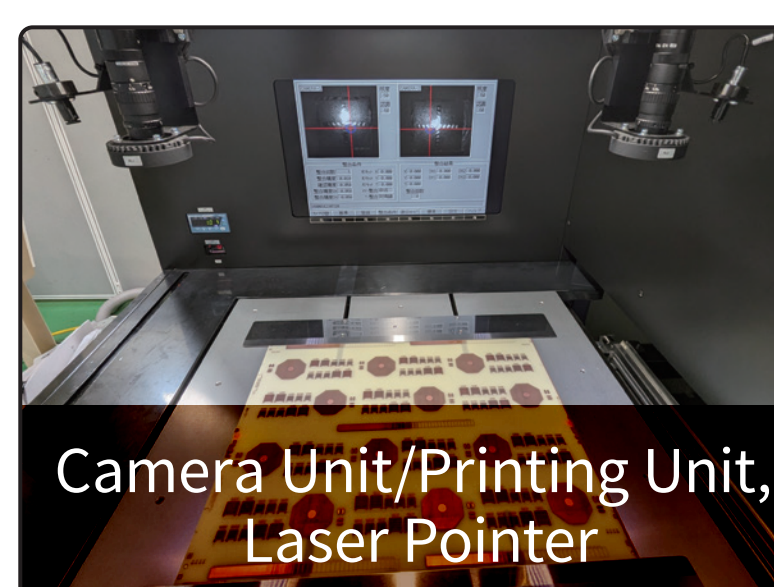
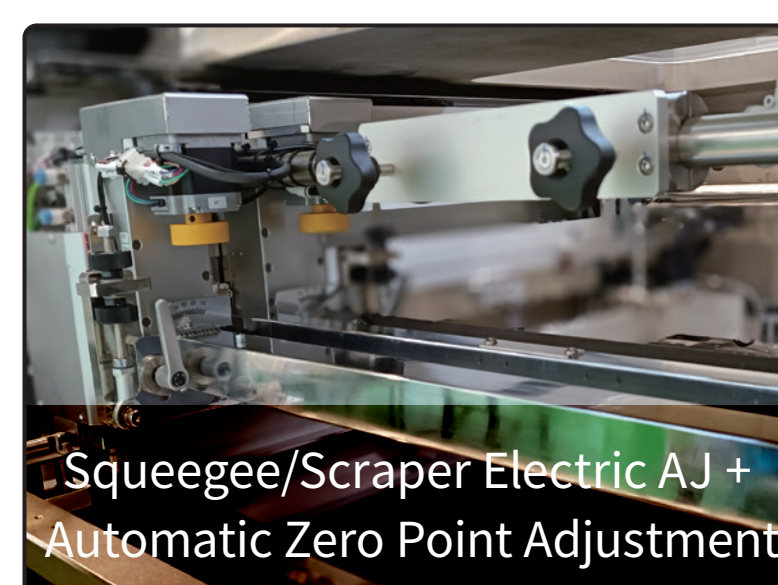


Reduce Power Consumption

Ecological Reduce power consumption

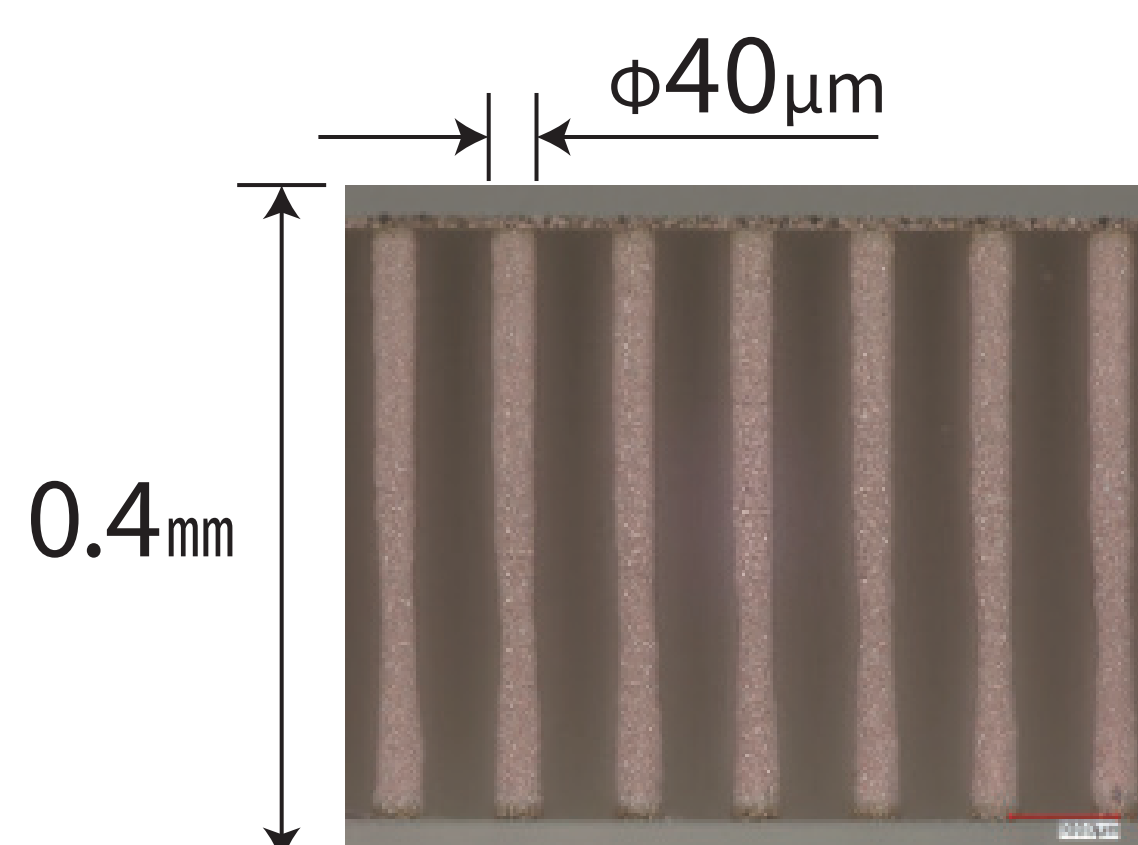


Various systems supporting printing

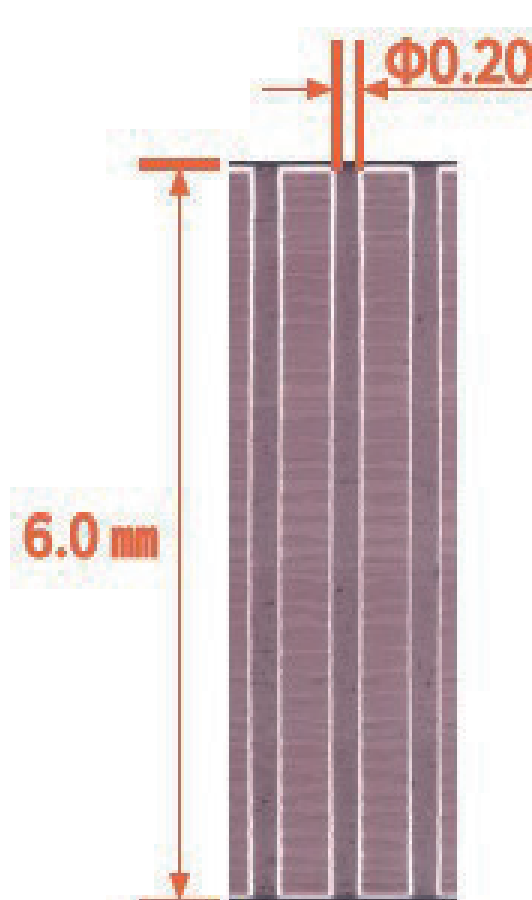


Small-diameters • High-aspect through holes • Voidless blind via filling

1. Small-diameter vias ($\phi 40\mu\text{m}$)



2. HLC-PCB with 30:1 aspect ratio



3. Blind Via Filling (Bottomed Holes)

